

# Ballistic thermal injection: controlling electron-phonon scattering at interfaces for long-lived plasmonic modulation



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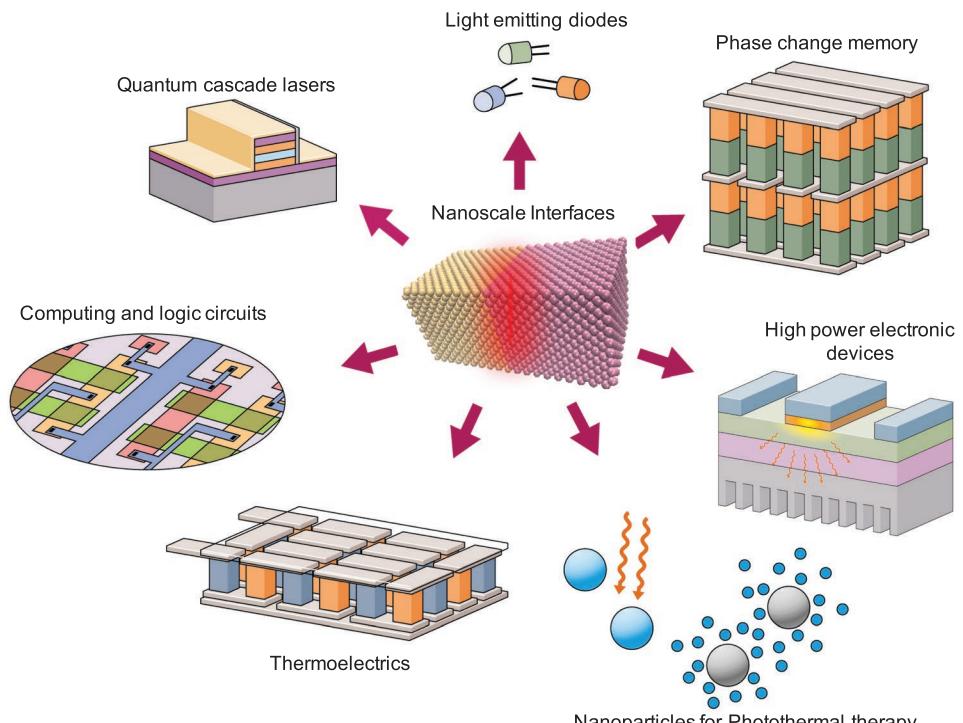
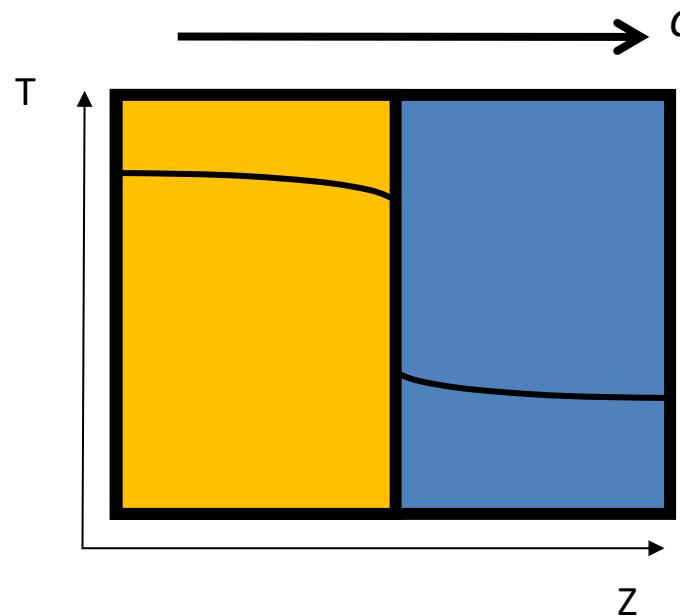


Prof. Josh  
Caldwell  
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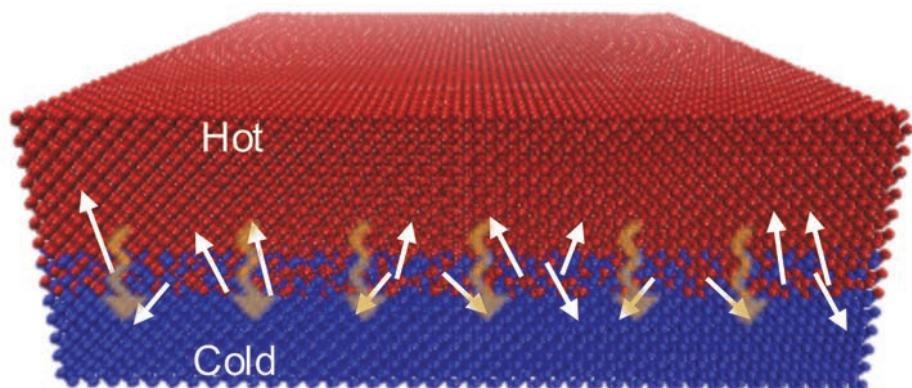


# Interfacial heat transport : Thermal boundary conductance

$$q = h_K \Delta T = \frac{1}{R_K} \Delta T$$

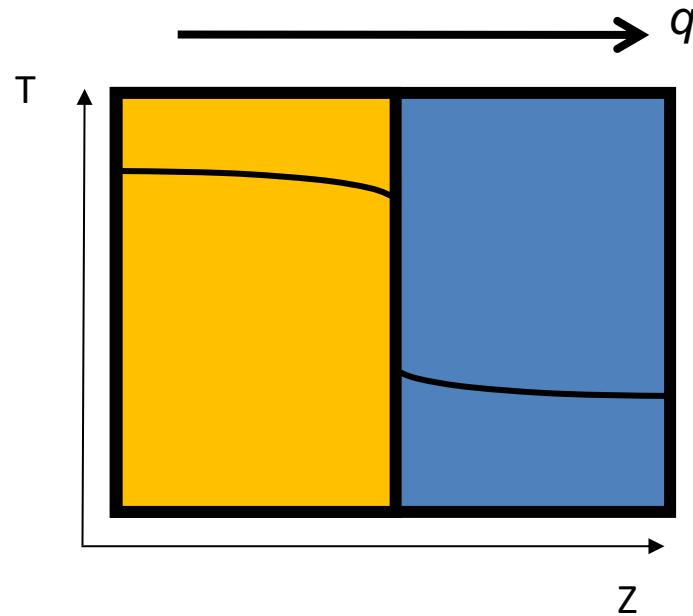


Recent Review  
*Advanced Functional Materials* 30, 1903857 (2020)



# Interfacial heat transport : Thermal boundary conductance

$$q = h_K \Delta T = \frac{1}{R_K} \Delta T$$



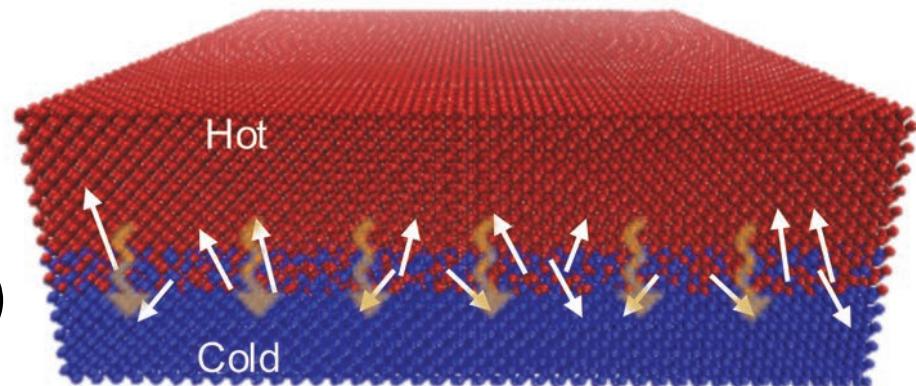
## Kapitza Length

$$L_K = \frac{\kappa}{h_K}$$

$$\kappa \sim 1 - 100 \text{ W m}^{-1} \text{ K}^{-1}$$

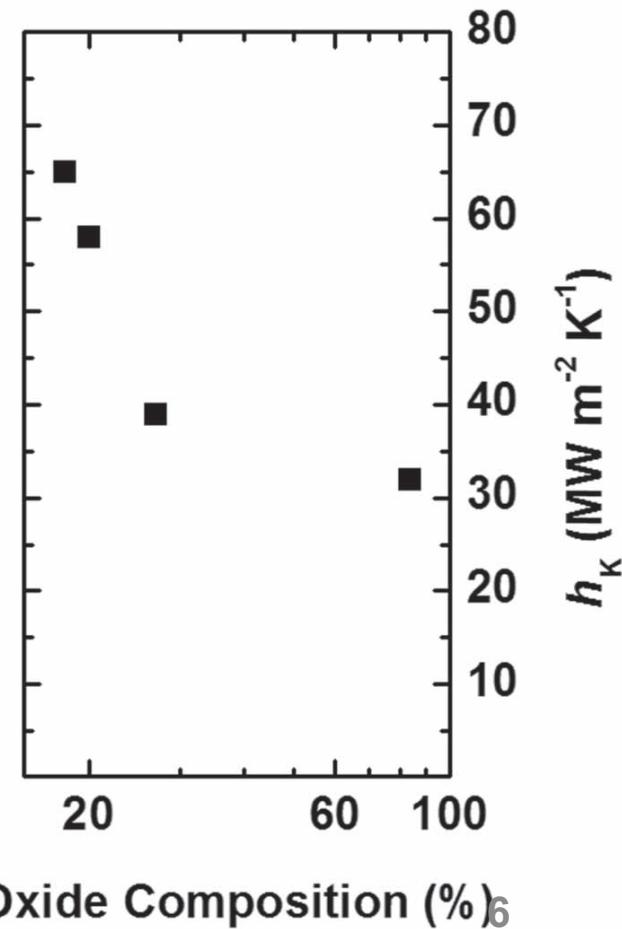
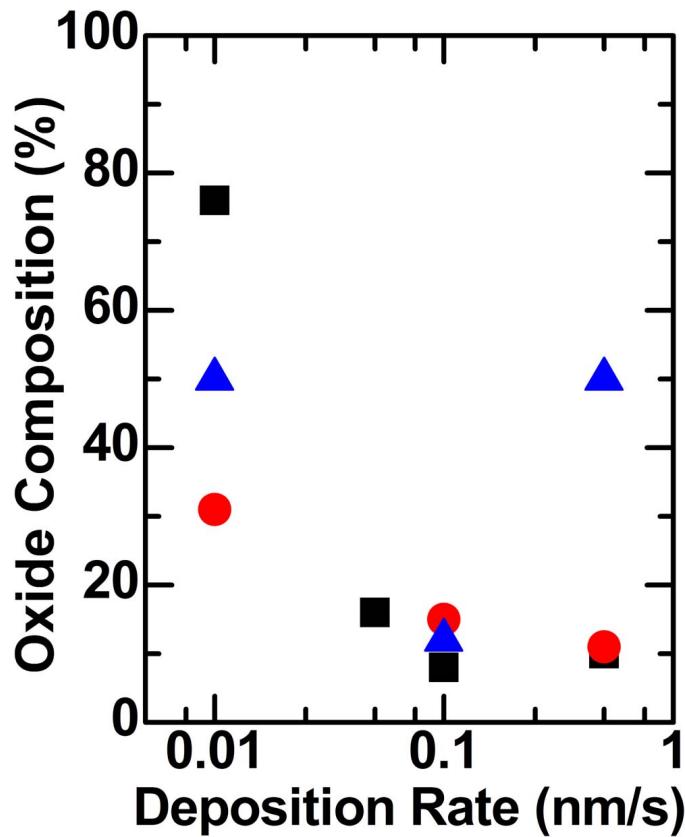
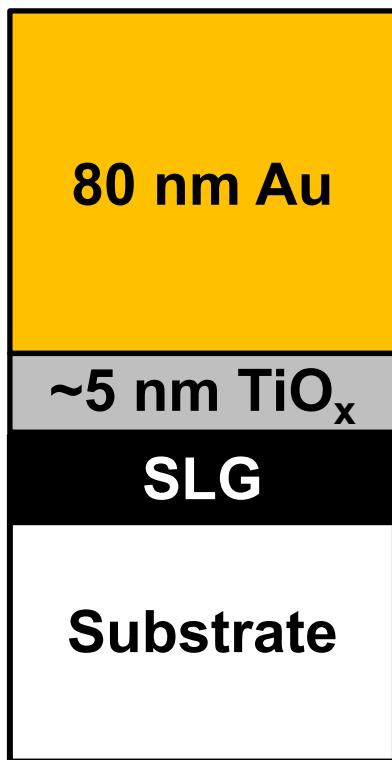
$$L_K \sim 10 \text{ nm} - 1 \mu\text{m}$$

Recent Review  
*Advanced Functional Materials* 30, 1903857 (2020)



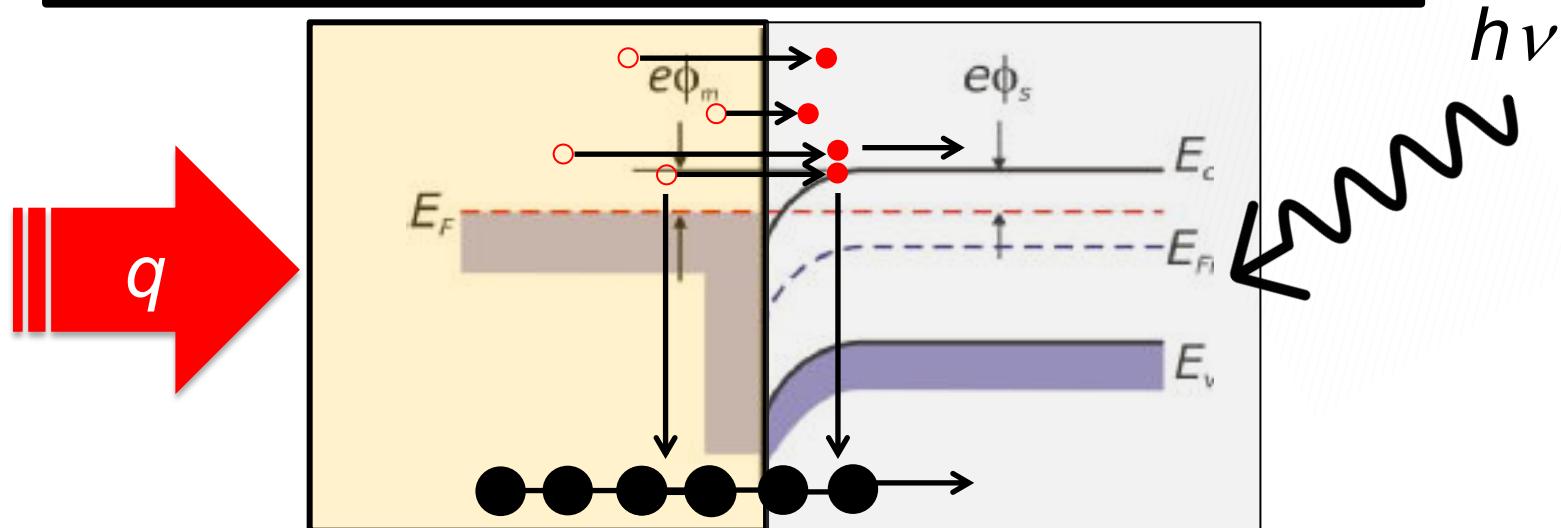
# Chemistry & TBC at metal/non-metal interfaces (phonons)

Au/TiO<sub>x</sub>/substrate with varying “x” (oxygen stoichiometry) to control thermal boundary conductance



# Interfacial heat transport : Thermal boundary conductance

But what are the electron-phonon heat transport mechanisms at interfaces?



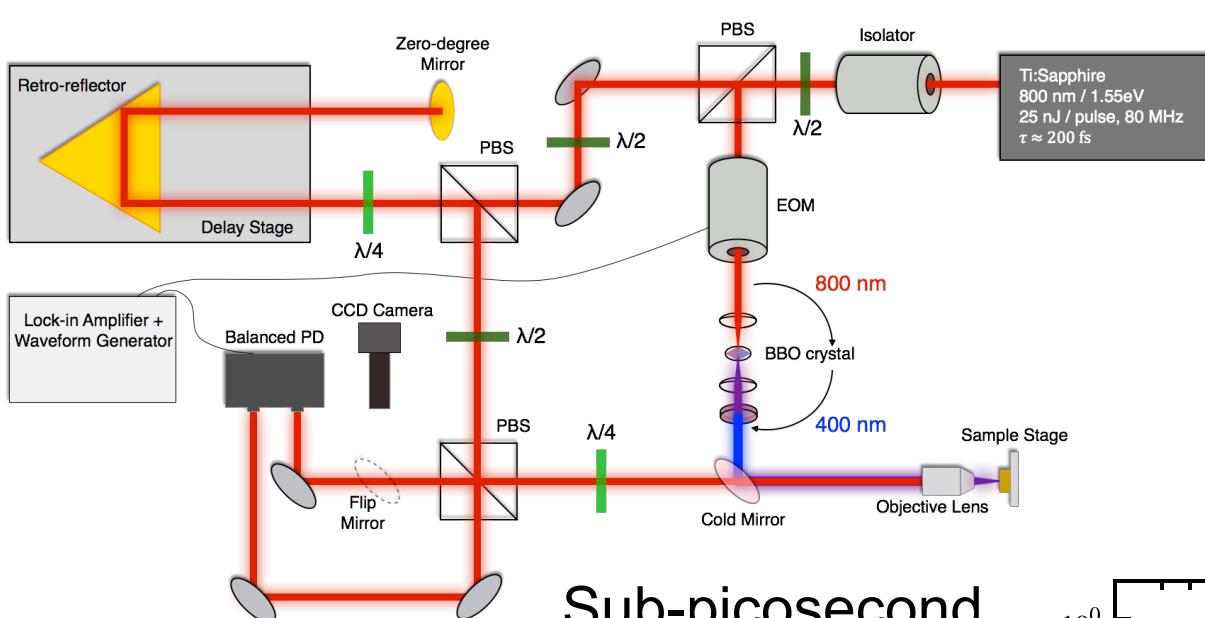
1. Electron energy transmission across metal/metal interfaces and electron-phonon coupling

Ex: Au/Ti adhesion layer/insulating substrate

2. Electron energy transmission across metal/non-metal interfaces to control carrier densities in non-metals

Ex: Au/doped CdO to control ultrafast plasmonic absorption in CdO

# Ultrafast pump-probe to measure EP coupling



20 nm Au

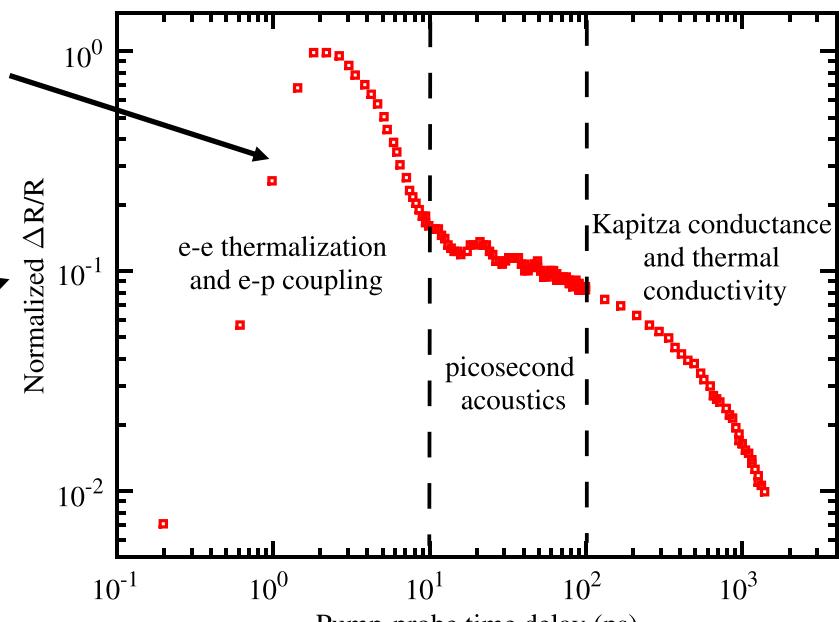
Sapphire

Energy no longer deposited in system

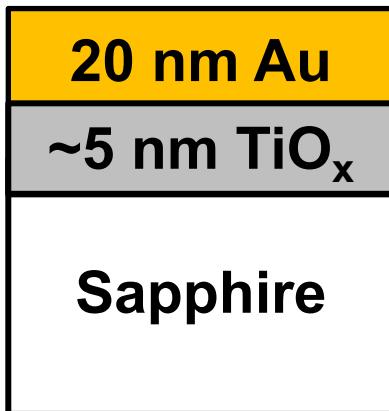
Sub-picosecond  
heat event

Directly related to temperature  
(advantage of probing metal)

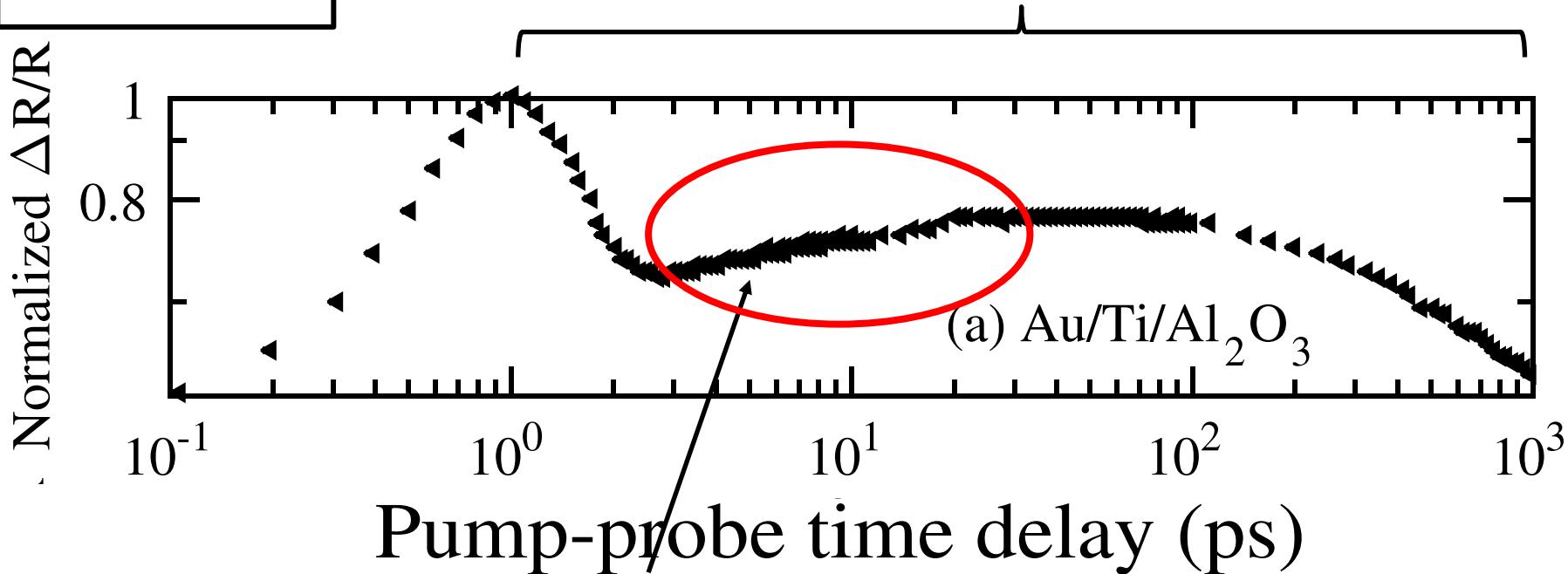
ACS Photonics 5, 4880



# Ultrafast pump-probe to measure EP coupling



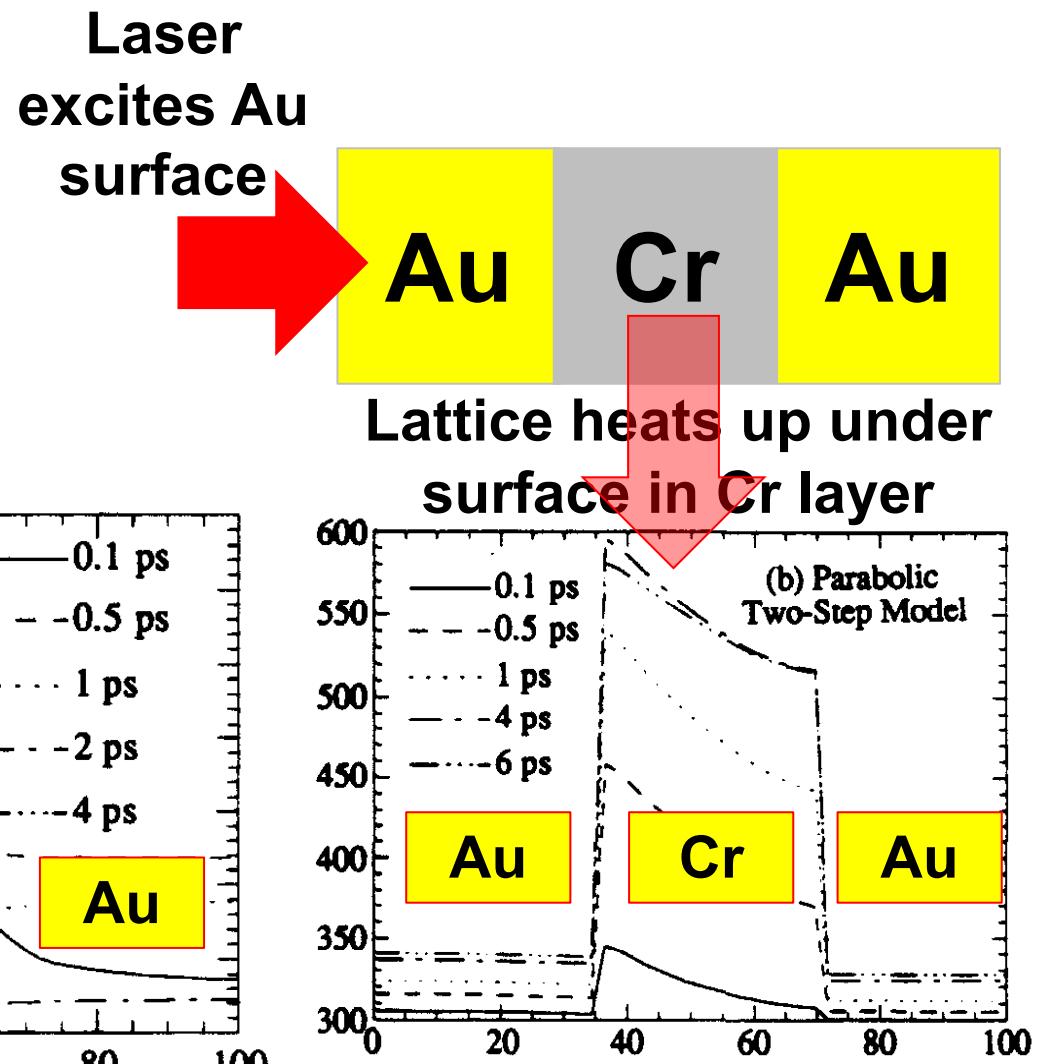
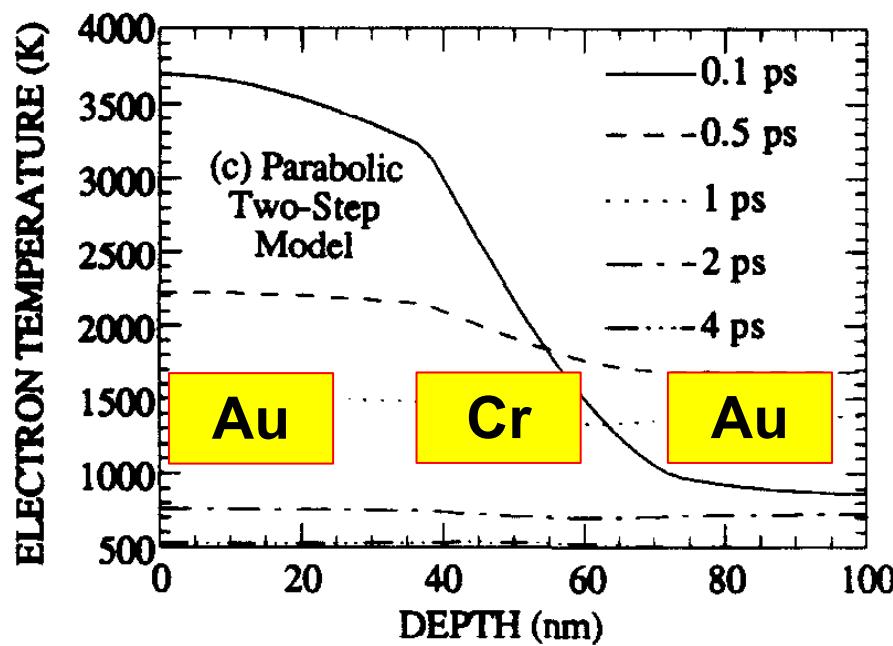
Energy no longer deposited in system



So why does temperature at surface increase when no energy is deposited in the system?

# Electron-phonon interactions at metal/metal interfaces

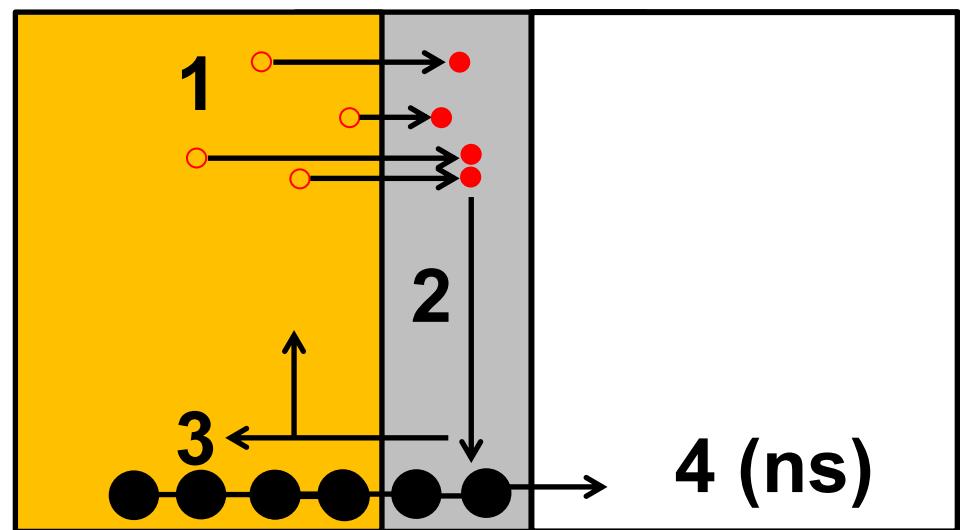
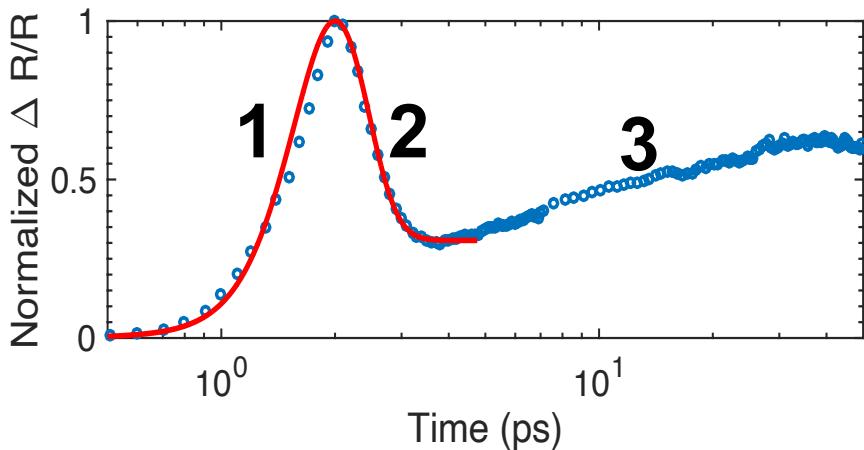
**Recall seminal  
predictions by Tien**  
Qiu and Tien, *IJHMT*  
37, 2789 (1994)



Au lattice slowly responds 10

# Ballistic thermal injection

- Excited electrons in metal from pulse do not thermalize with lattice and deposit their energy to lattice in sub-surface layer
- Ballistic transport of electron energy through gold into titanium

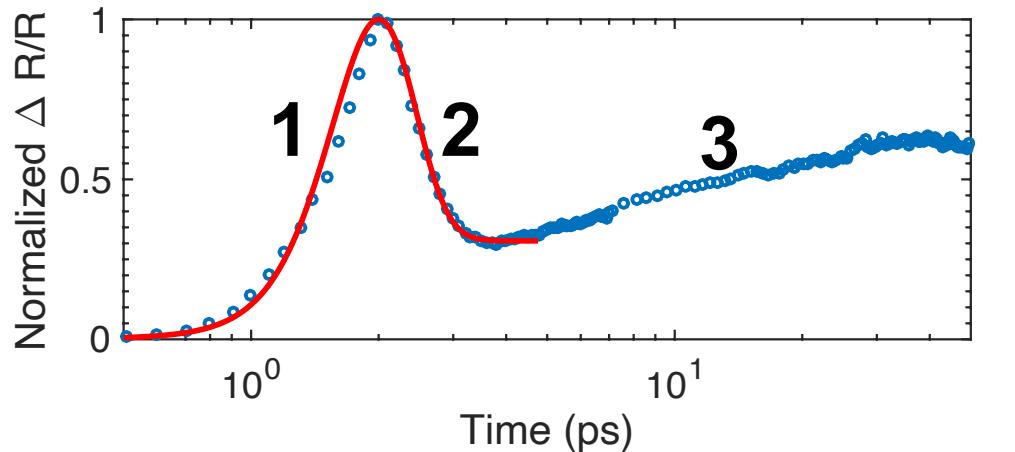


When would we see this effect?

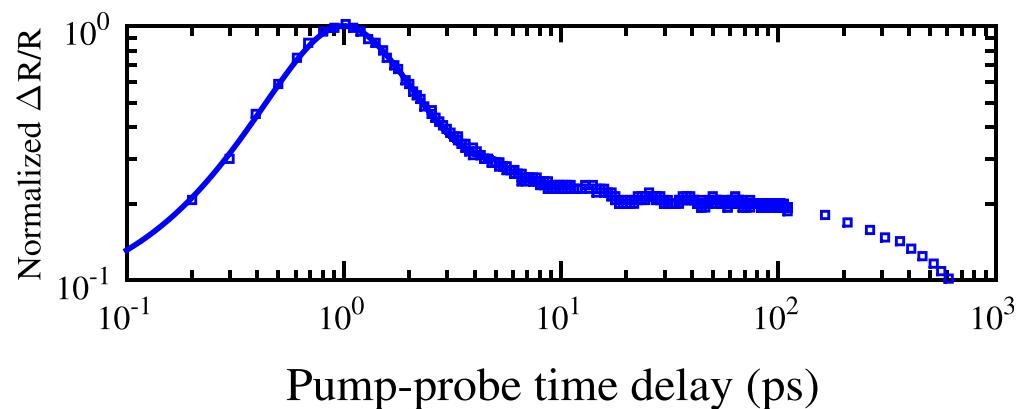
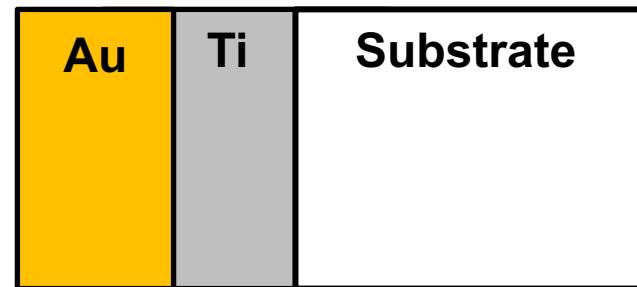
1. Metal/metal or metal/non-metal interfaces with large differences in electron-phonon coupling factor
2. Films with thicknesses less than electron-phonon mean free path
3. Interfaces with very little electron-electron thermal resistance

# TDTR measurements of time scales of noneq. transport

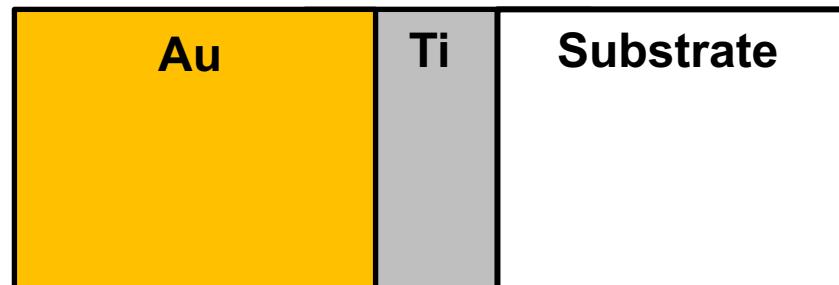
**Hypothesis:** If Au thickness ( $d_{\text{Au}}$ ) is thicker than electron-phonon mean free path ( $\lambda_{\text{ep}}$ ), nonequilibrium at interface will be negligible and “back heating” (time regime 3) will not be observed



$$d_{\text{Au}} < \lambda_{\text{ep}}$$

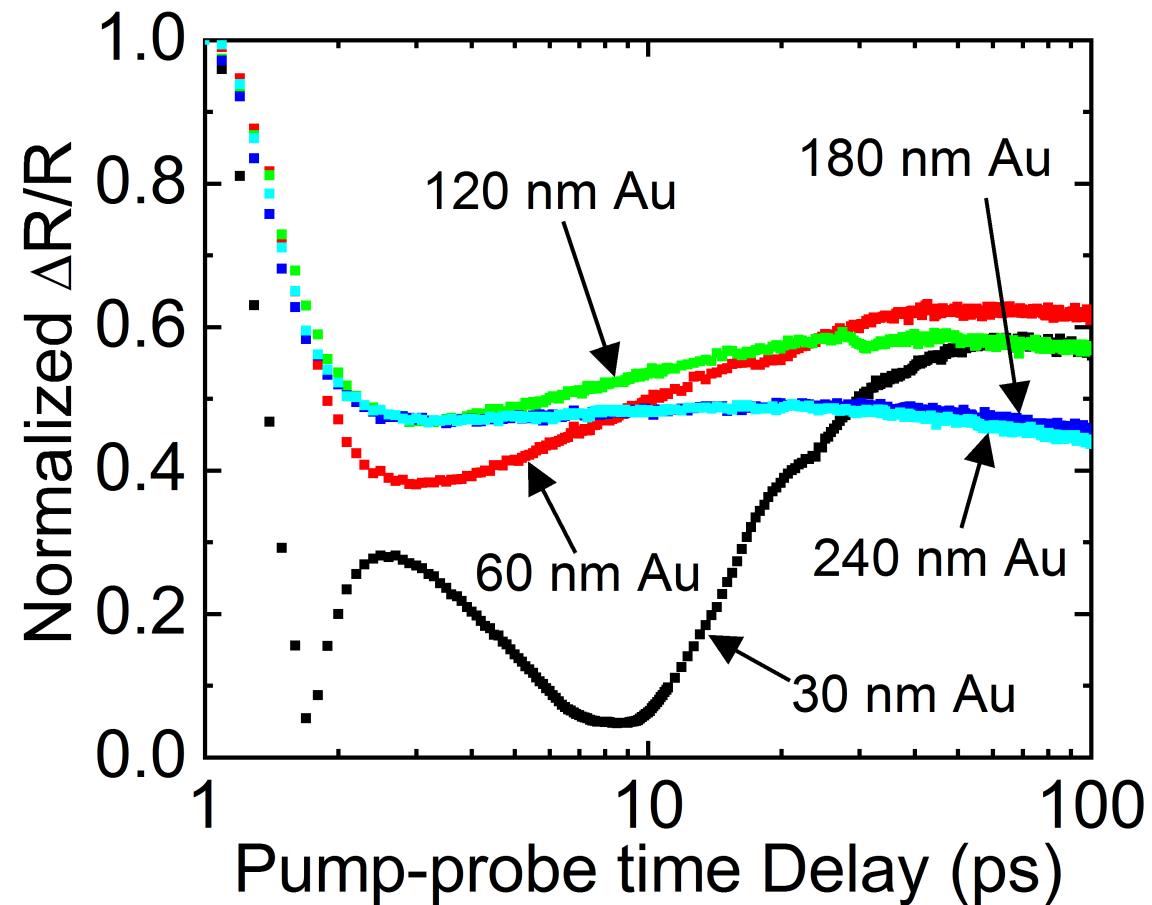


$$d_{\text{Au}} > \lambda_{\text{ep}}$$



# Ballistic electron-phonon mean free path in gold

**Hypothesis:** If Au thickness ( $d_{\text{Au}}$ ) is thicker than electron-phonon mean free path ( $\lambda_{\text{ep}}$ ), nonequilibrium at interface will be negligible and “back heating” (time regime 3) will not be observed



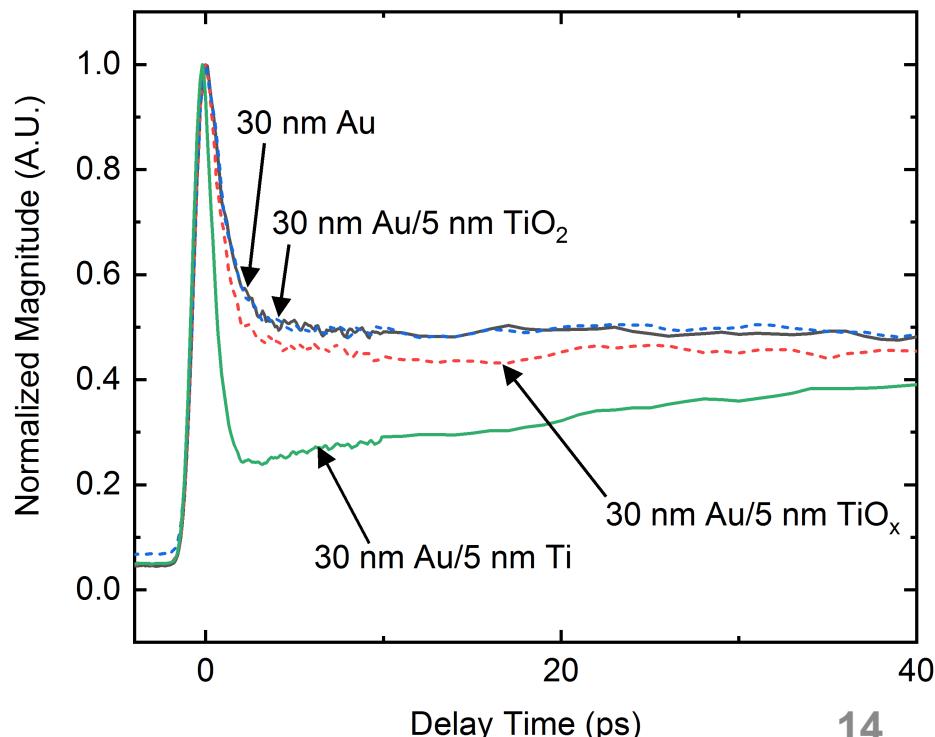
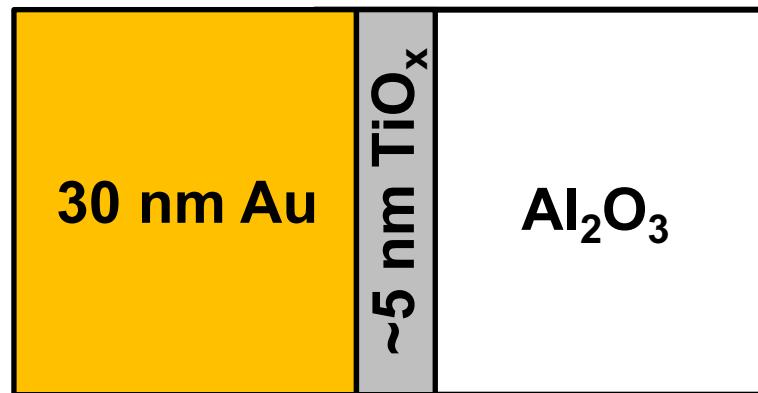
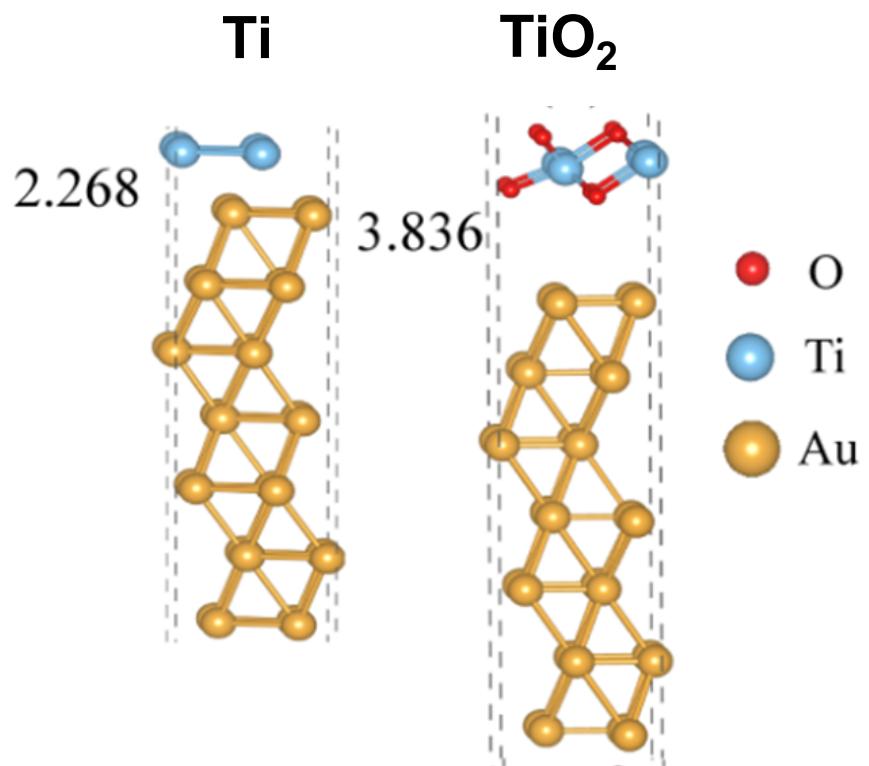
$$\lambda_{\text{ep},\text{Au,calc}} \approx \sqrt{\frac{\kappa_{\text{electron}}}{G}}$$

$$\approx 79 - 117 \text{ nm}$$

$$\lambda_{\text{ep},\text{Au,meas}} \approx 90 - 130 \text{ nm}$$

# Bonding at metal/metal interfaces controls heat injection

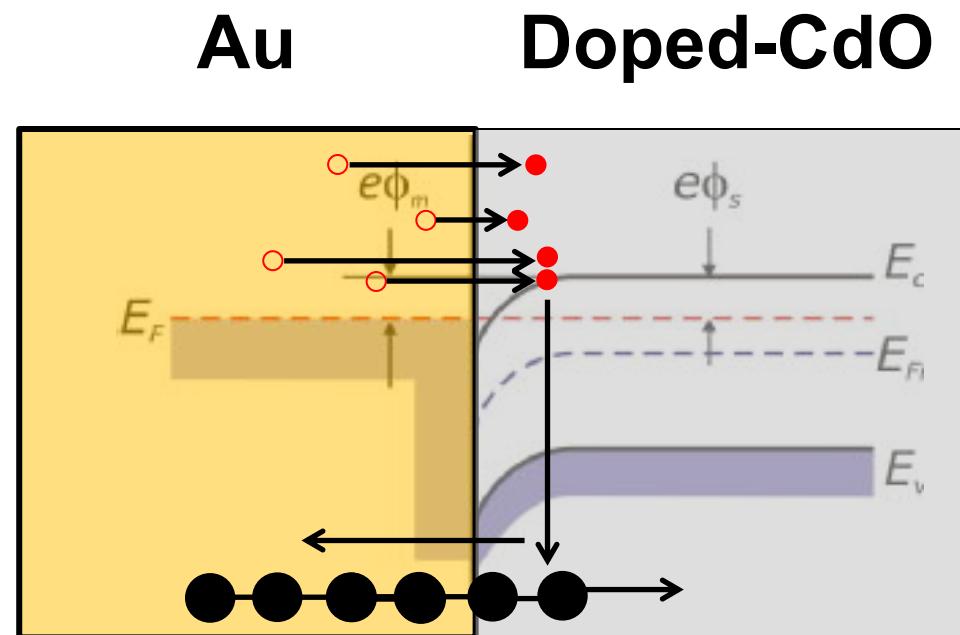
- Electron injection from Au to Ti needed to observed “back heating”
- Ti oxygen stoichiometry impacts electron injection to Ti



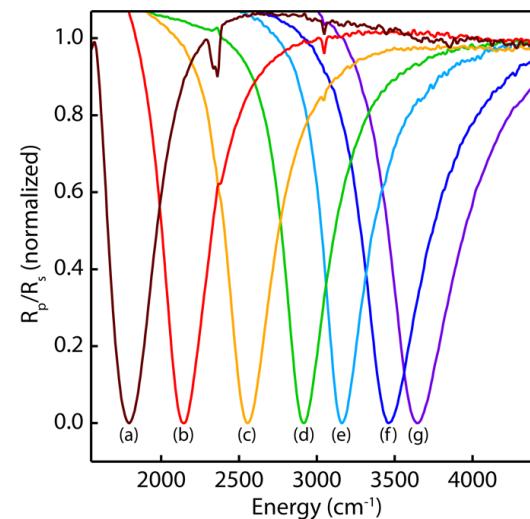
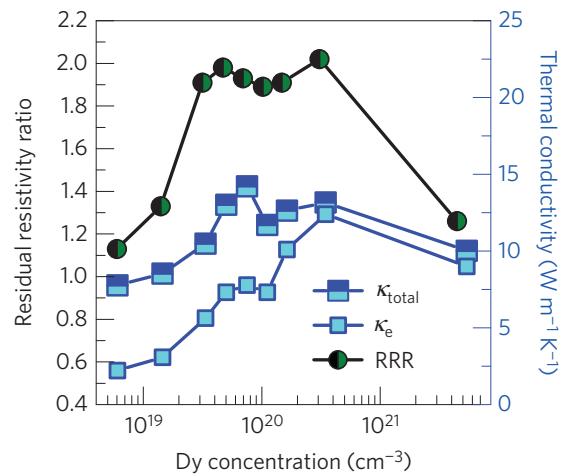
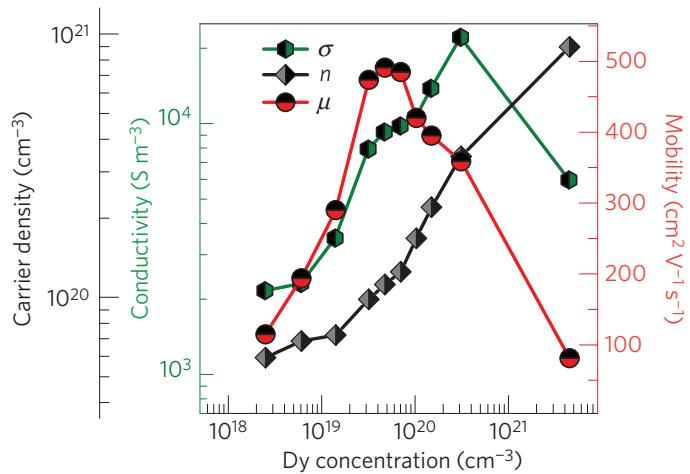
# Nonequilibrium at metal/doped non-metal interfaces

- Consider ohmic contact between metal and doped non-metal
- Vary carrier concentration in non-metal

- Electron injection from Au to interfacial layer must occur to observe “back heating” effect
- Will not occur when interface is insulating



# CdO – a gateway for mid-IR plasmonics



*ACS Photonics* **4**, 1885

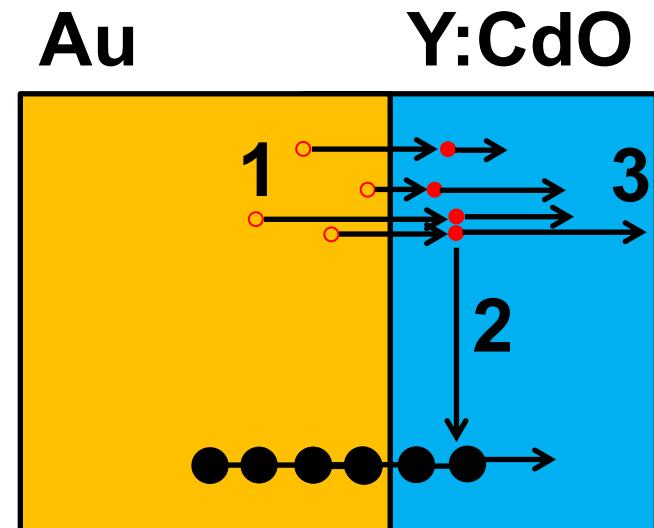
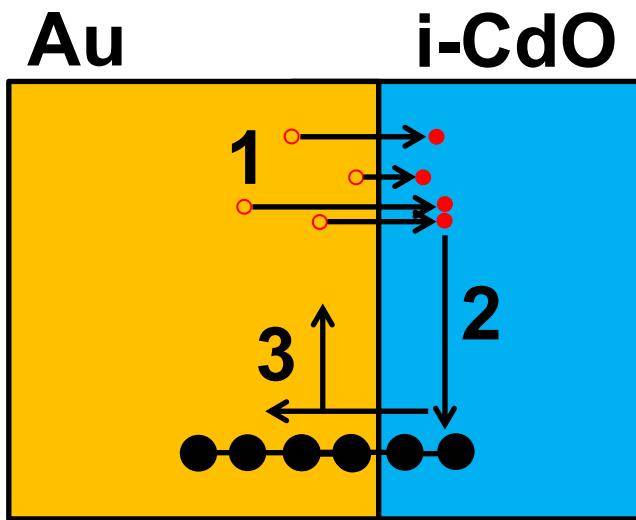
- Large electron mobility in CdO results in large electronic thermal conductivity
- Doping concentration tunes electronic conductivity and IR absorption

*Nat. Mat.* **14**, 414

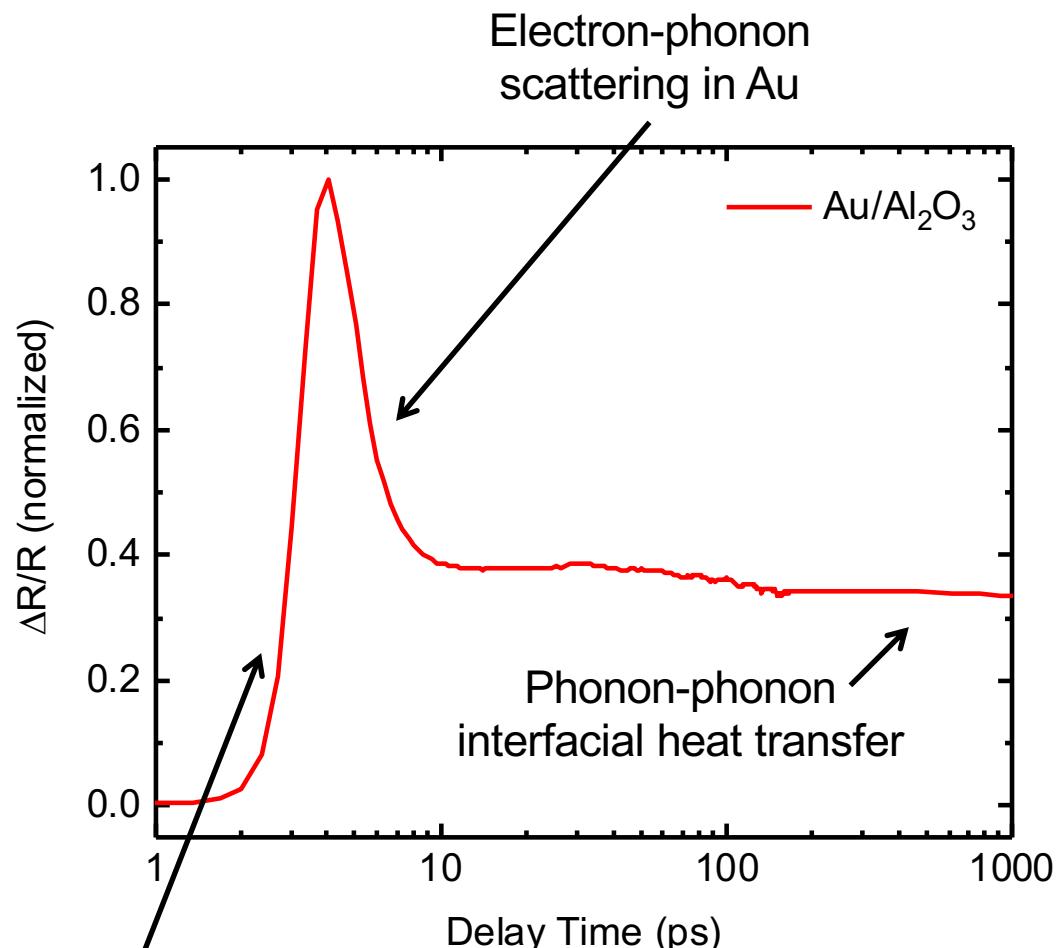
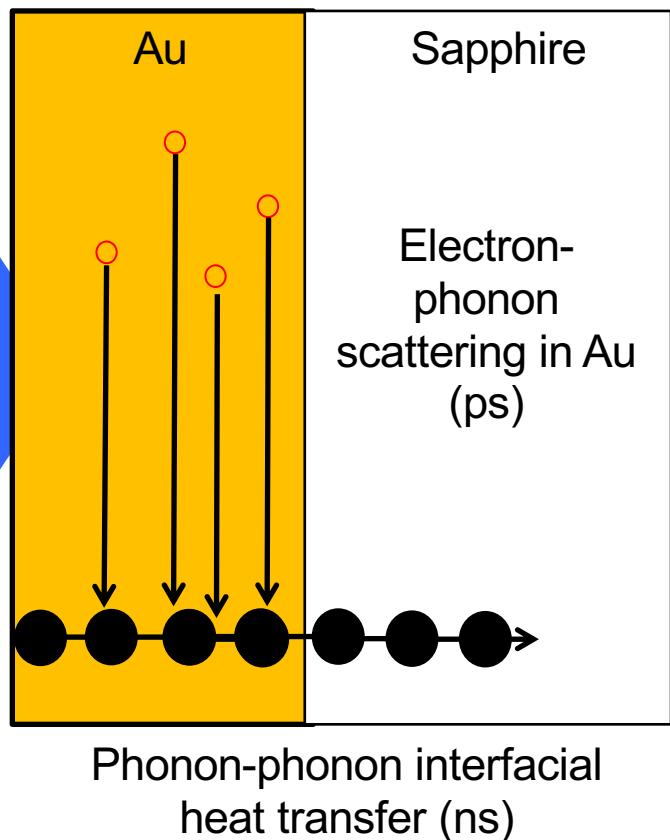
*Appl. Phys. Lett.* **108**, 021901

# Nonequilibrium processes at Au/CdO interfaces

Doping will control electron-electron TBC and electron thermal conductivity in CdO, vary “back heating”

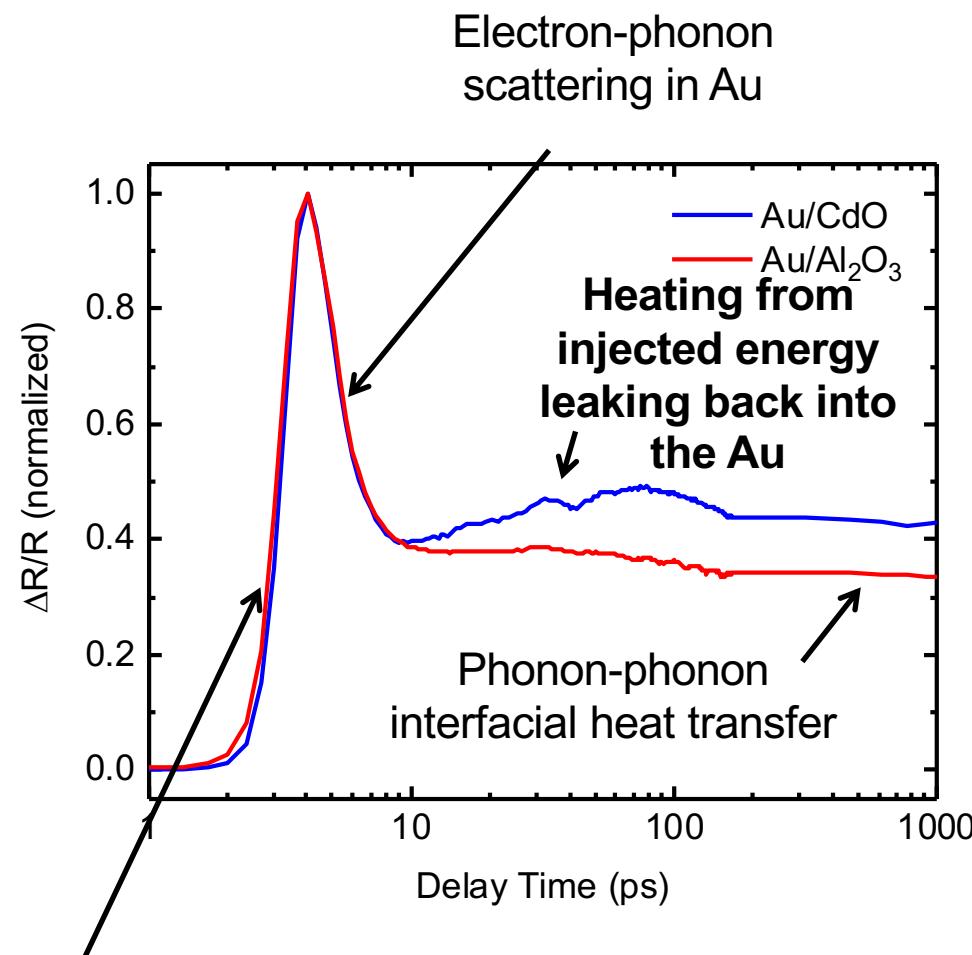
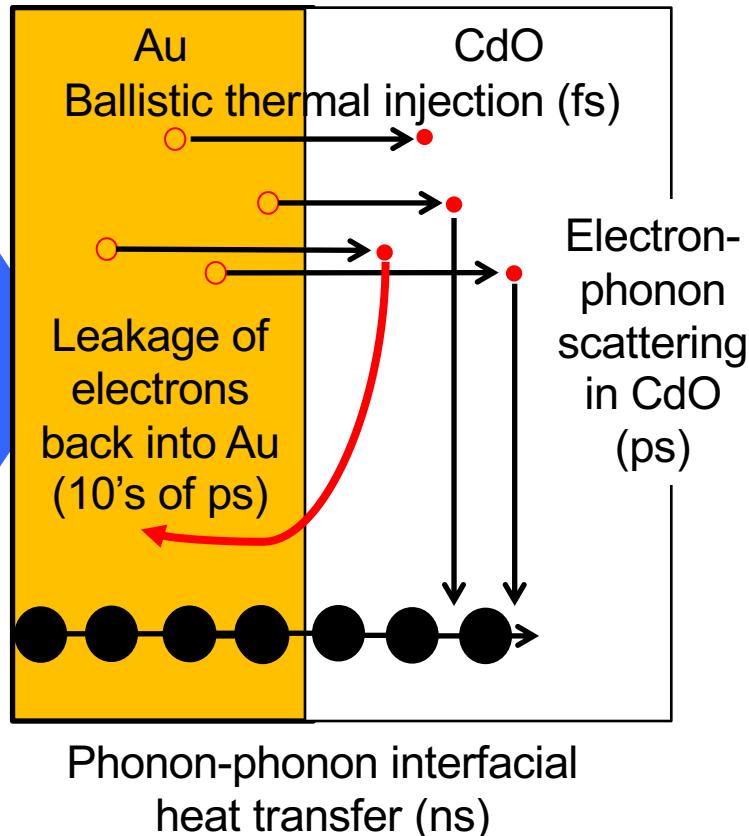


# Nonequilibrium processes at Au/CdO interfaces



~sub picosecond pulsed laser absorption in Au

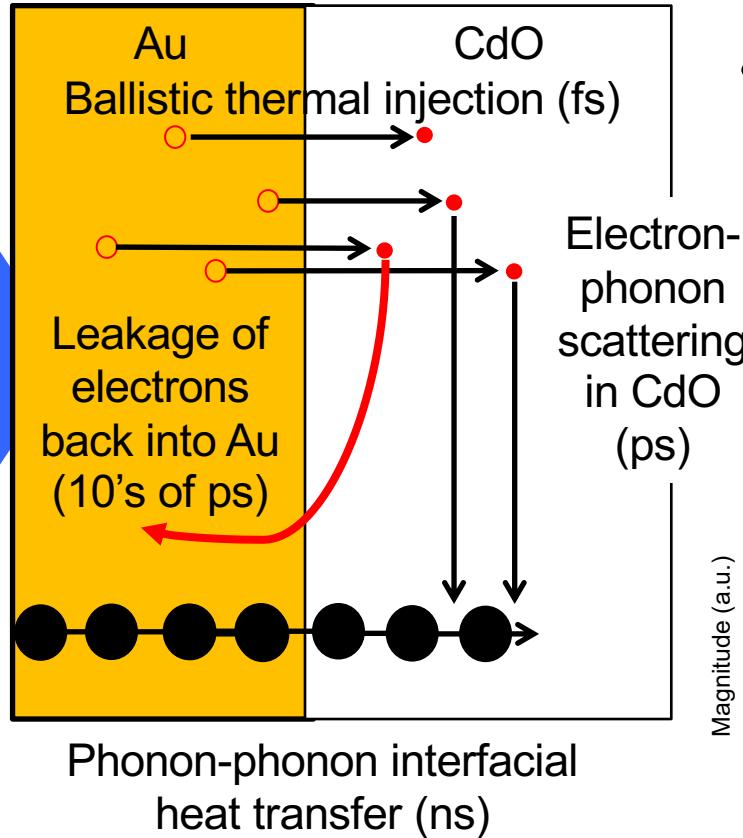
# Nonequilibrium processes at Au/CdO interfaces



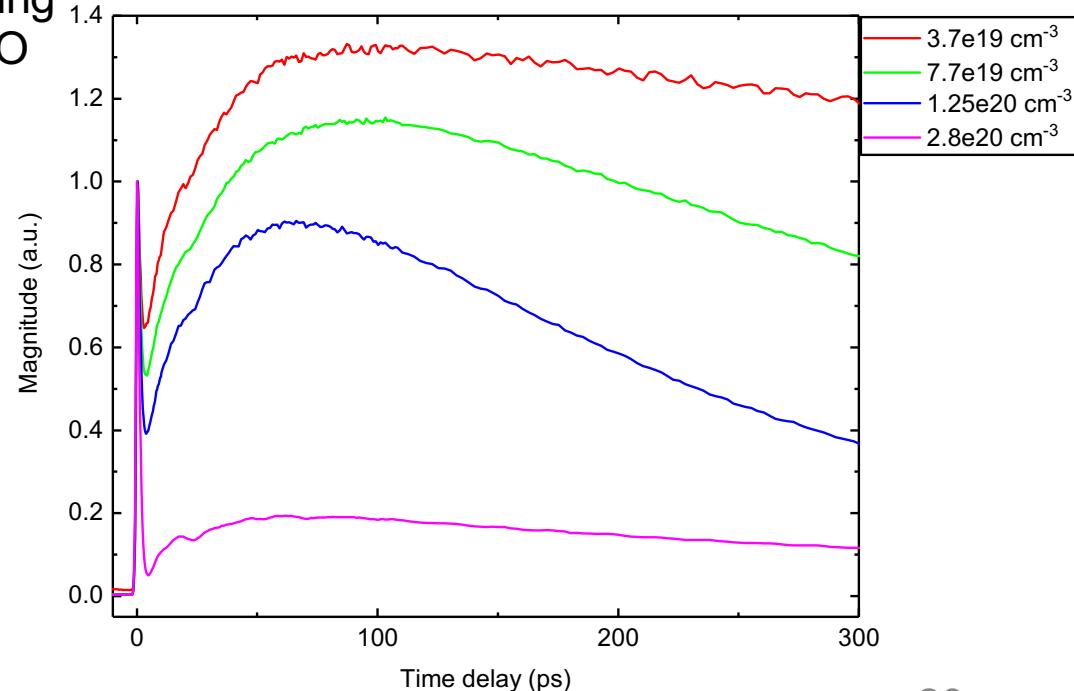
~sub picosecond pulsed laser  
absorption in Au + **charge  
injection into CdO**

# Nonequilibrium processes at Au/CdO interfaces

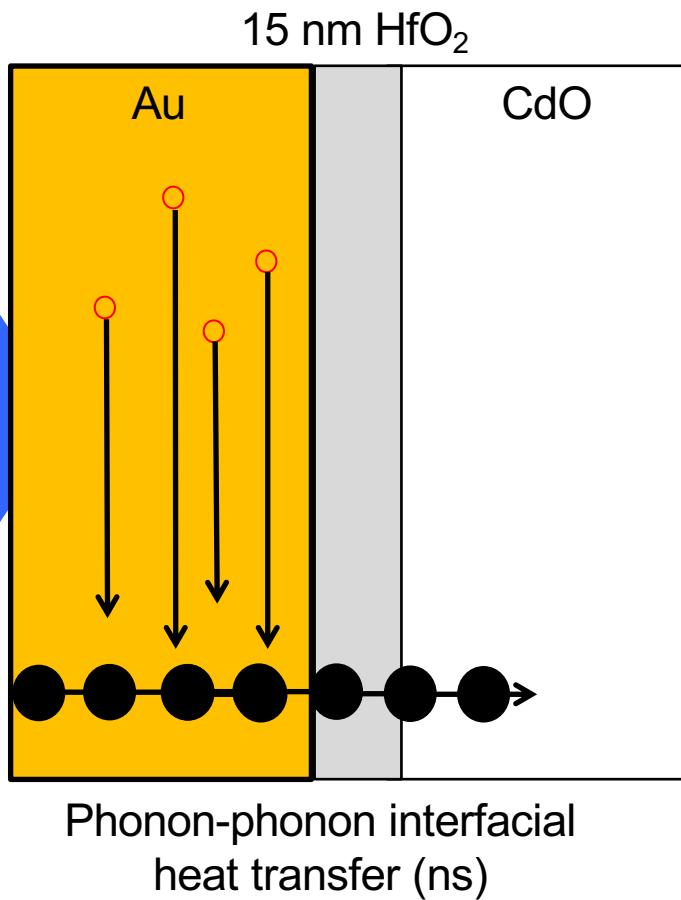
- Doping of CdO dictates amount of “electron leakage” back into Au



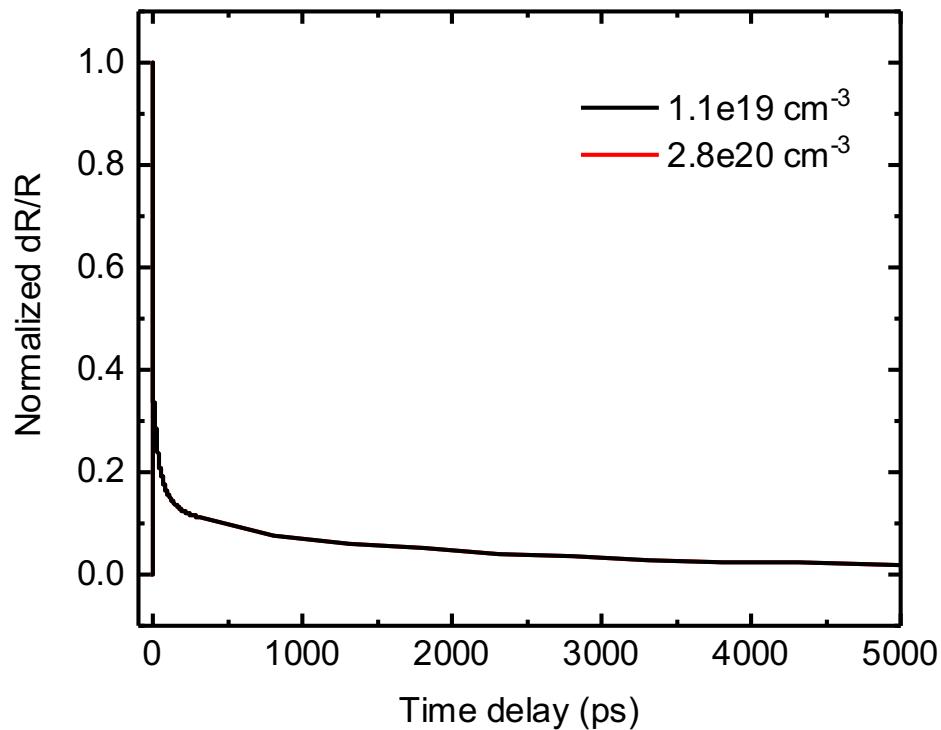
- Lower resistivity + higher e-ph coupling in CdO, less electronic back heating into gold contact



# Nonequilibrium processes at Au/CdO interfaces



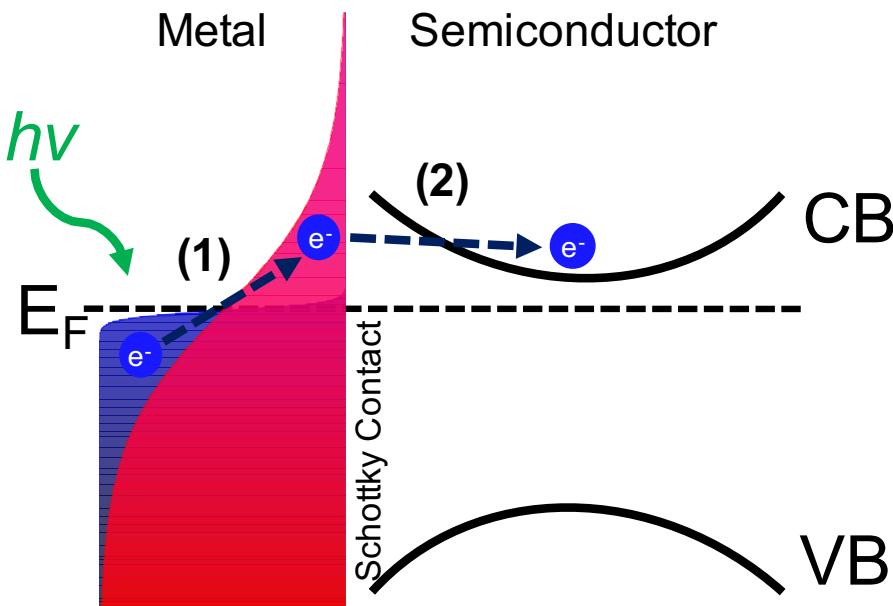
- Transparent buffer layer stops ballistic electrons, but allows light to transmit
- No back-heating observed for any dopant concentration!



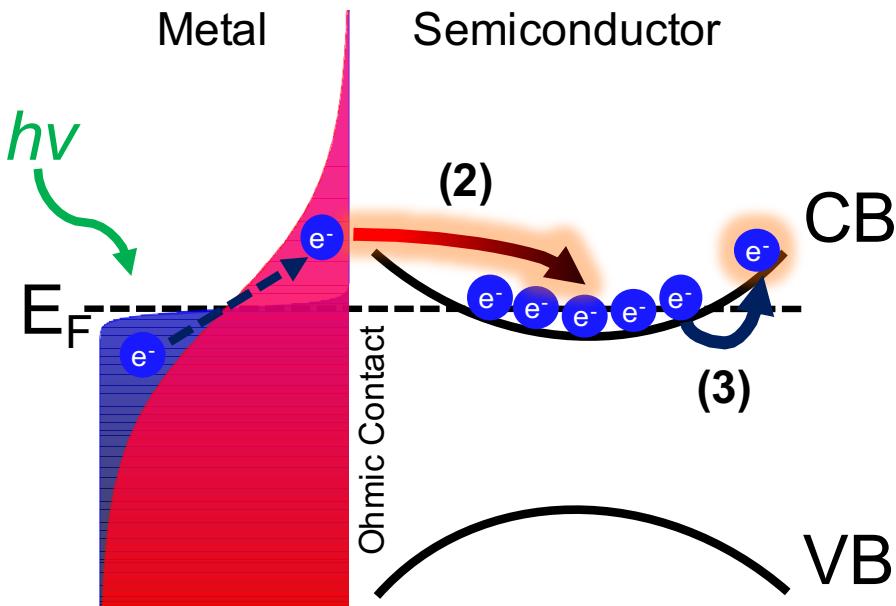
# Ballistic thermal injection

- Can enable a “transient thermal diode” effect
- Energy easily transmitted across interface when traveling ballistically
- Slowly “goes back” across the interface when diffusive
- Is this just hot electron injection (charge)?
  - Too slow of process
  - Can further rule this out by monitoring CdO plasmon response

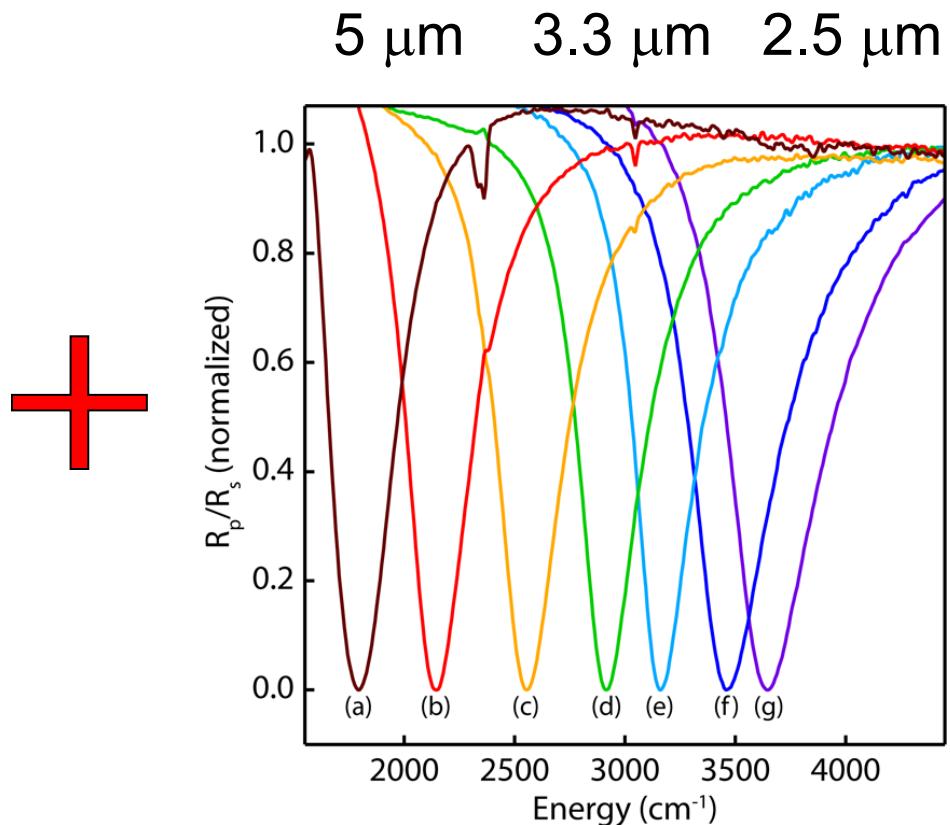
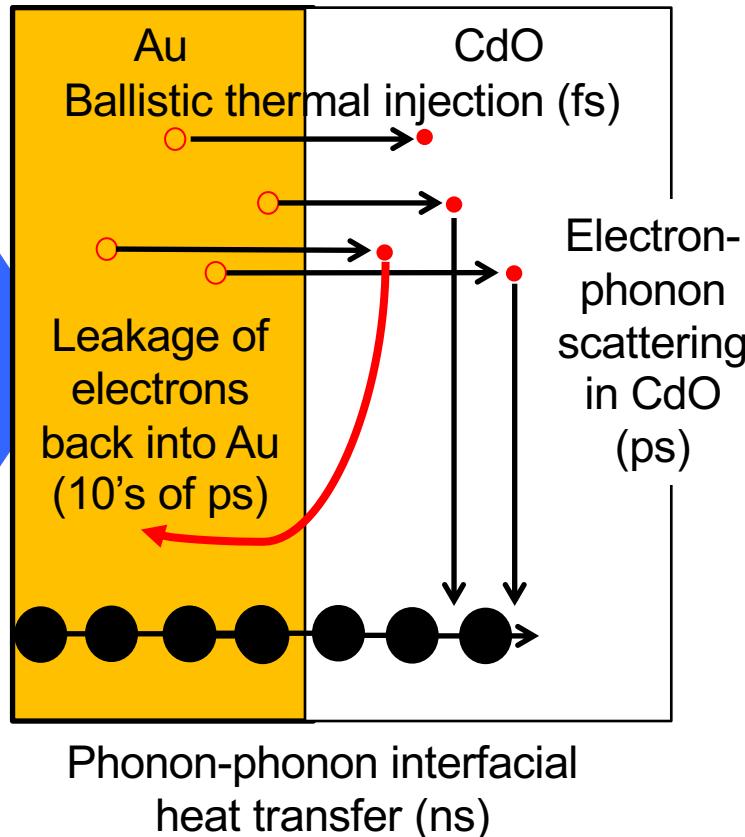
a) Hot electron injection  
(Charge transfer)



b) Ballistic thermal injection  
(Energy transfer)

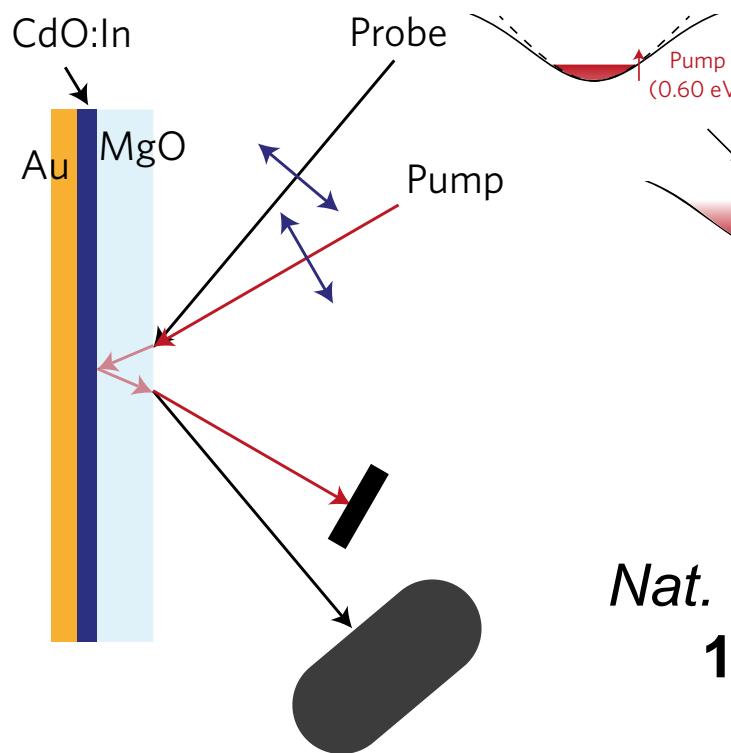


# Nonequilibrium electrons to control CdO plasmons

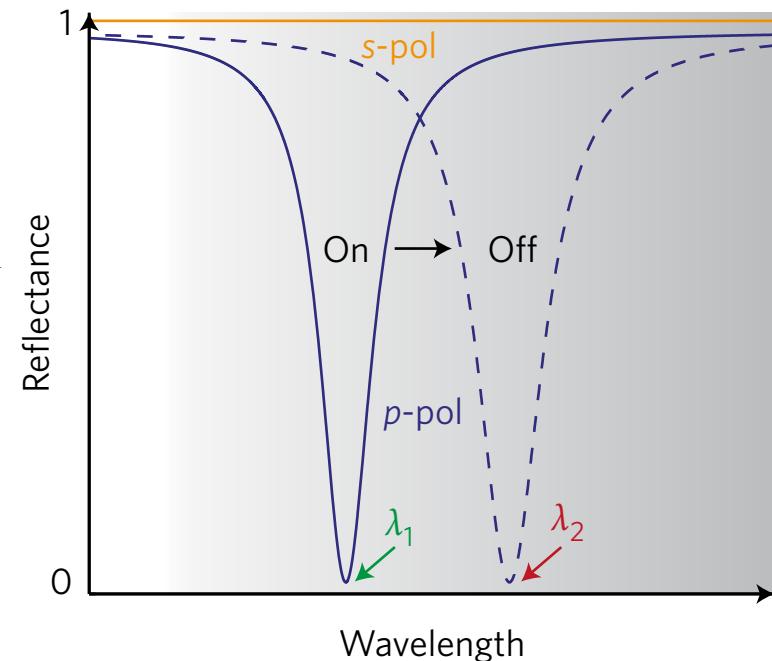


Increasing carrier concentration

# Pumping electrons can impact plasmon response



*Nat. Photonics*  
11, 390

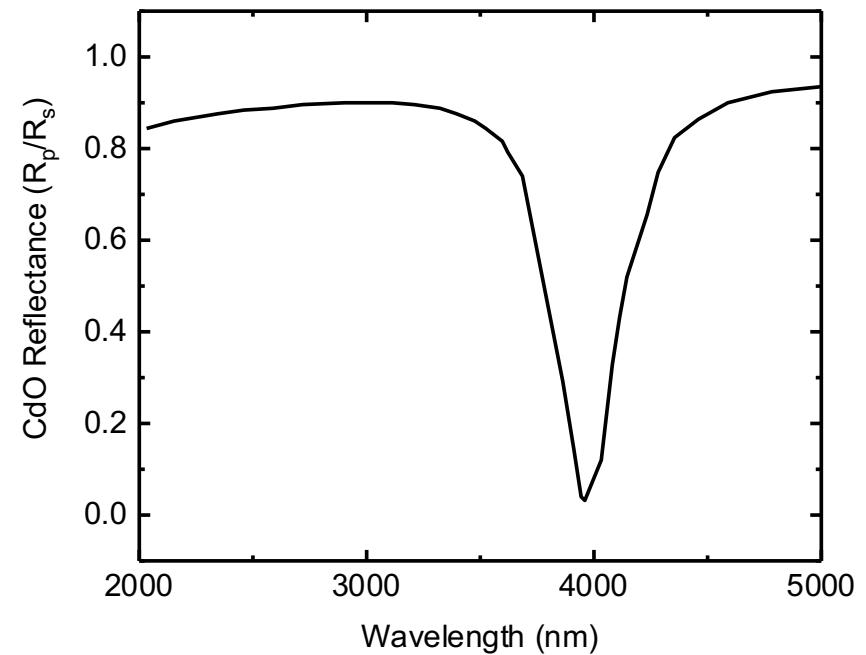
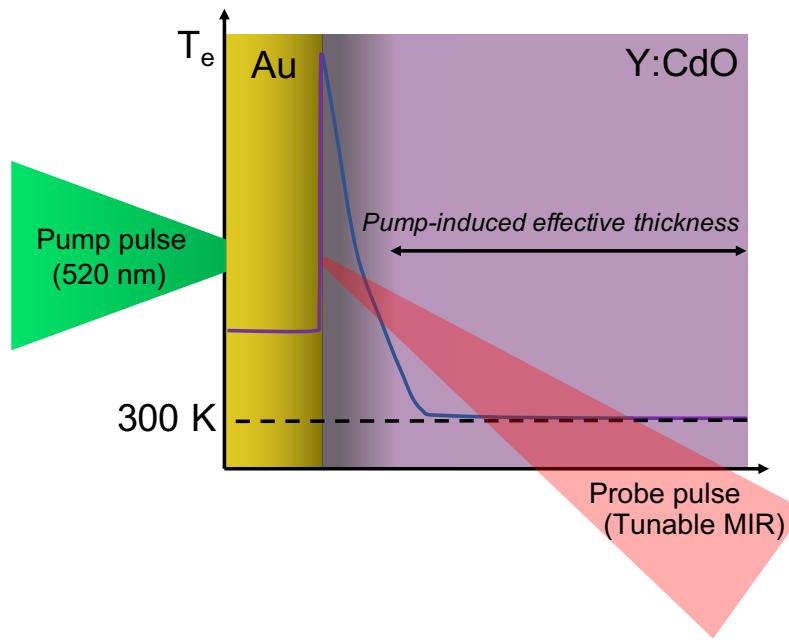


- Exciting electrons in CdO (intraband) can change effective mass and red shift plasmon response
- Requires specific wavelength photons and laser conditions
- **Can we use BTI to inject heat into CdO and impact plasmons?**

# Pump electrons in Au, probe plasmon in CdO

How is the IR plasmon response of CdO impacted by ballistic thermal injection?

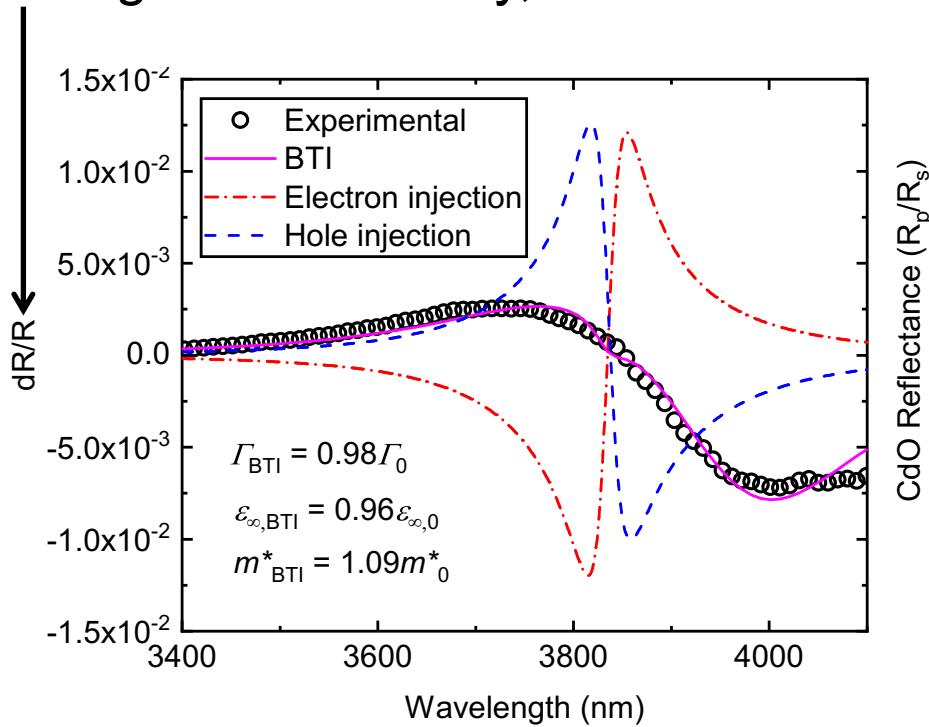
Au/CdO/sapphire absorption response



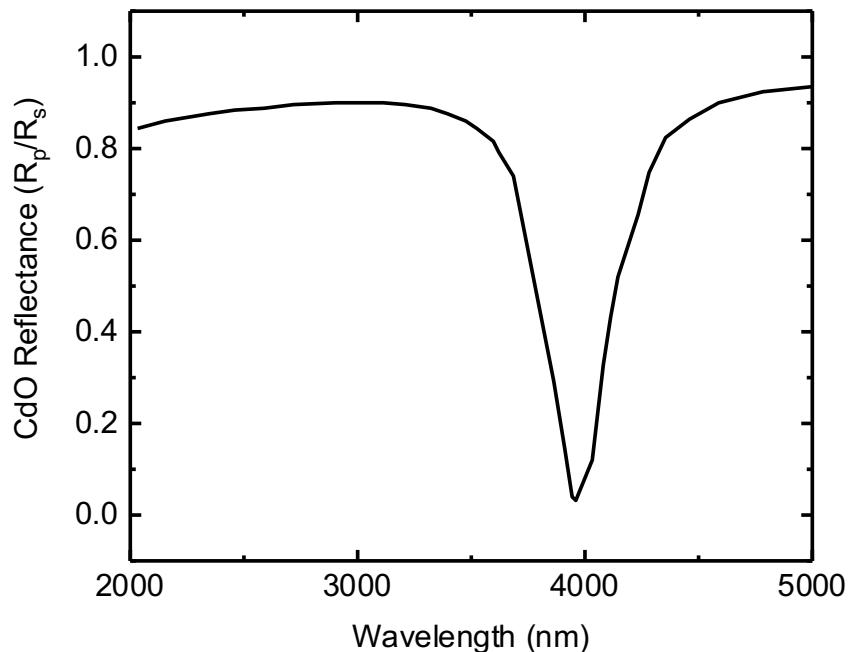
# Pump electrons in Au, probe plasmon in CdO

## Asymmetric red shift in ENZ plasmon mode due to BTI

Note we are measuring  
*change* in reflectivity,  $dR$

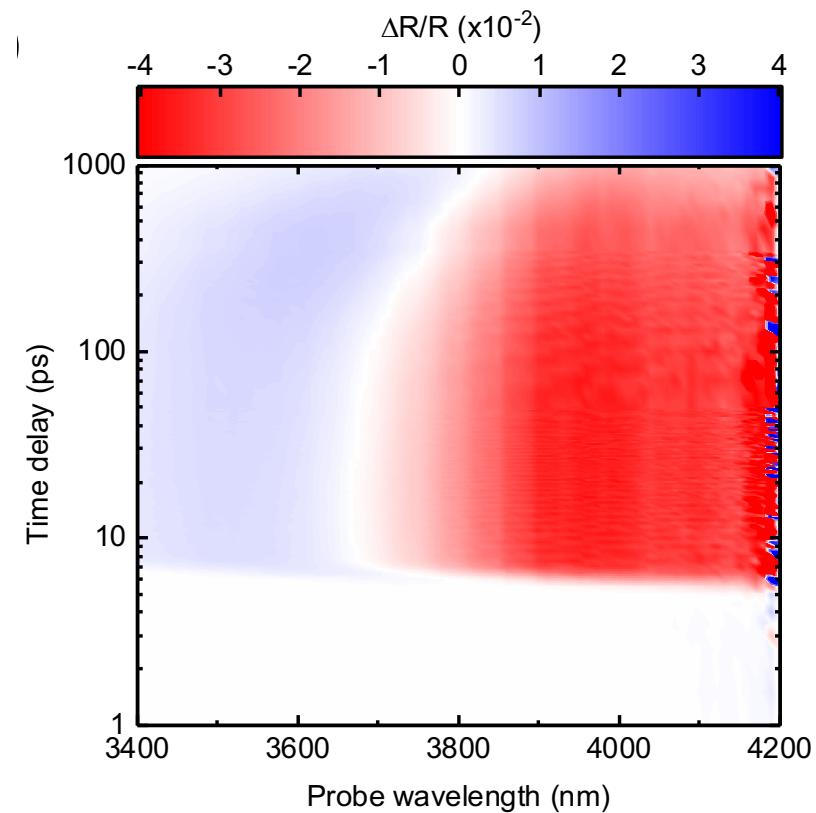
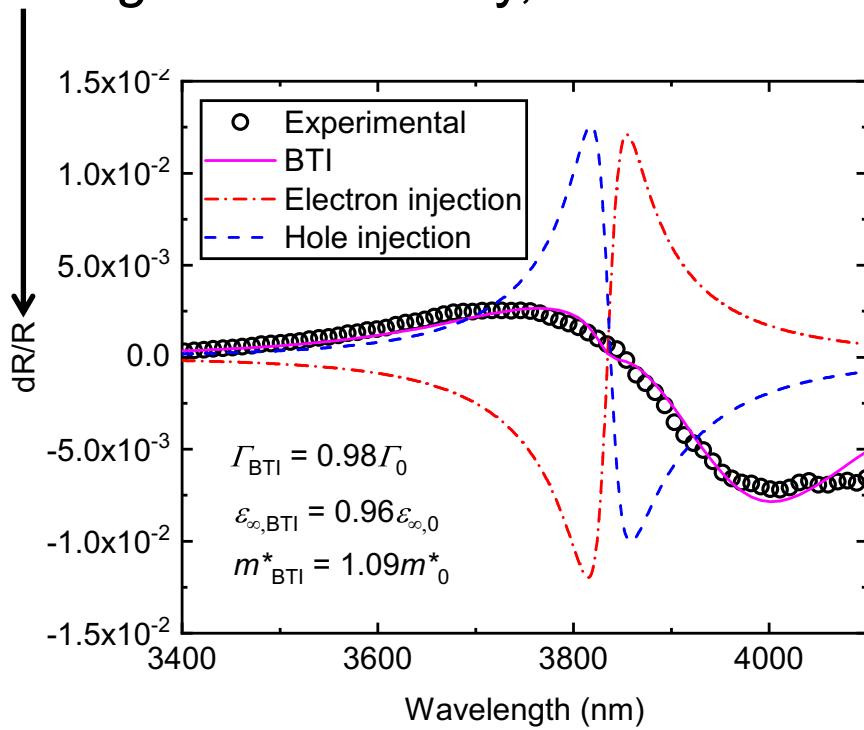


Au/CdO/sapphire absorption response

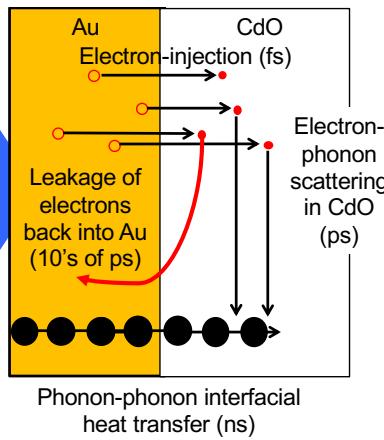


## Asymmetric red shift in ENZ plasmon mode due to BTI

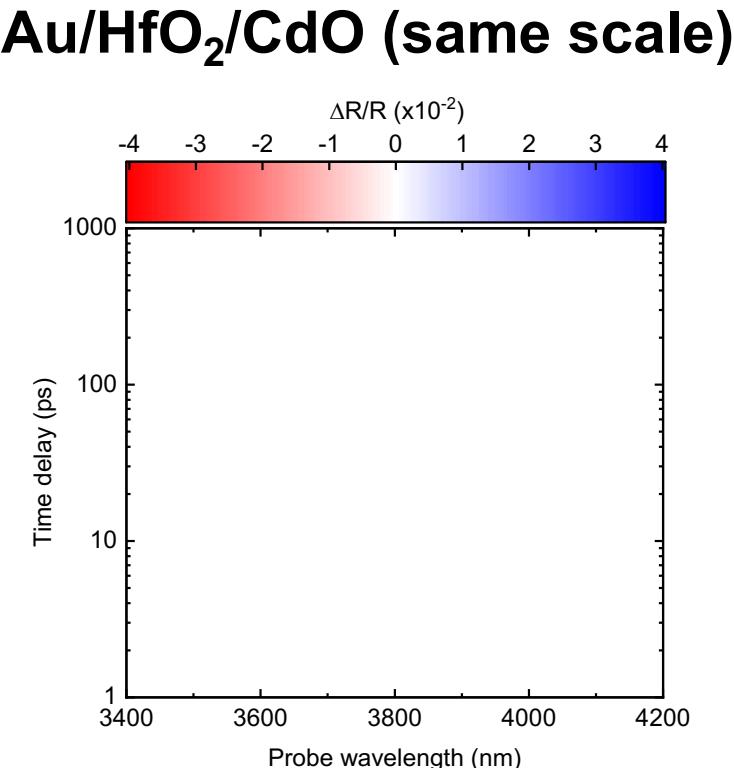
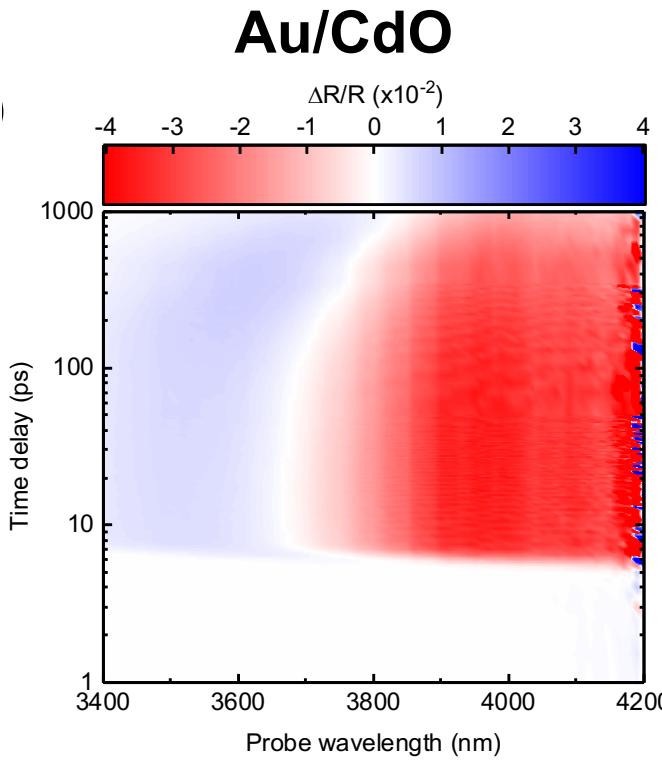
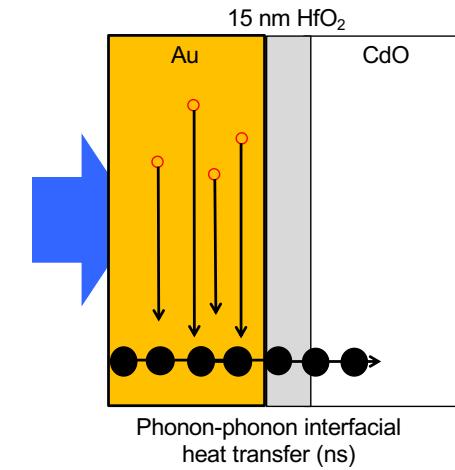
Note we are measuring  
*change* in reflectivity,  $dR$



# And it's not an optical artifact



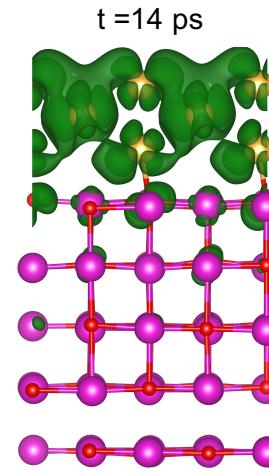
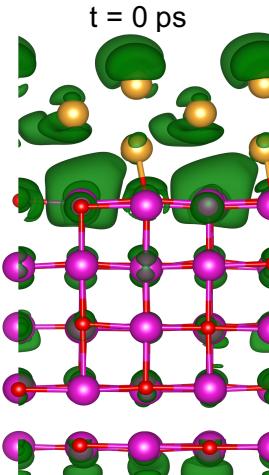
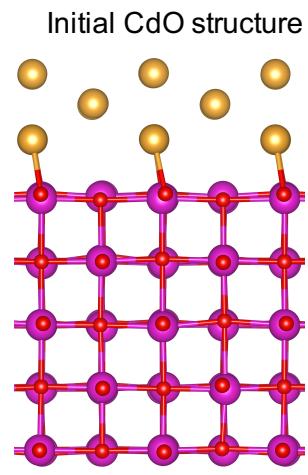
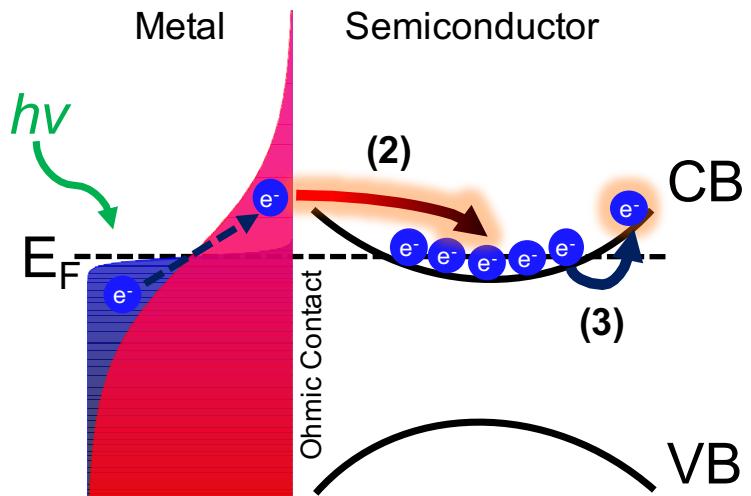
15 nm  $\text{HfO}_2$  layer prevents any electron energy from moving from **Au** to **CdO**, resulting in no measurable response



# Nonequilibrium electron thermal transport processes control electrons, phonons and plasmons



## Ballistic thermal injection (Energy transfer)



Legend:  
- Au  
- Cd  
- O